



Product Change Notification

Change Notification #: 115245 - 00
Change Title: Intel® Compute Module HNS2600TPR,
 PCN 115245-00, Product Material,
 Replacement of BMC DDR3 chip
Date of Publication: January 09, 2017

Key Characteristics of the Change:

Product Material

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material: * Jan 24, 2017

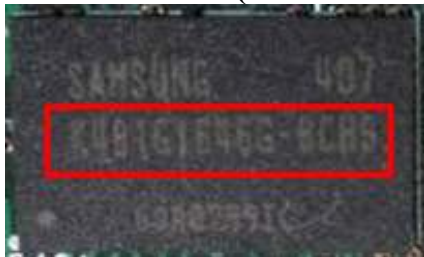
* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

Intel is implementing the following change:

Intel is replacing the current BMC DDR3 memory chip K4B1G1646G-BCH9 (G38649-001) with new K4B1G1646I-BCK0 (J37656-001). Intel reports validation completed with passing results. The replacement component is identical in form, fit and function.

Current DDR3 (G38649-001)



New DDR3 (J37656-001)



Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from these changes, but encourages customers to understand the change and determine the impact on their applications. For that reason, Intel recommends that the customers perform a standard level of evaluation.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Pre Change PBA	Post Change TA	Post Change PBA
HNS2600TPR	943948	H94938-004	H26989-271	H94938-005	H26989-272

PCN Revision History:

Date of Revision: January 9, 2017	Revision Number: 00	Reason: Originally Published PCN
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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

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